

Specification for Approval

Customer: _____

Model Name: _____

Supplier Approval			Customer approval
R&D Designed	R&D Approved	QC Approved	
<i>Peter</i>	<i>Peng Jun</i>		

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1. Scope

This specification defines general provisions as well as inspection standards for TFT module supplied by AMSON electronics.

If the event of unforeseen problem or unspecified items may occur, naturally shall negotiate and agree to solution

2. General Information

TFT

ITEM	STANDARD VALUES	UNITS
LCD type	3.5" TFT	--
Dot arrangement	320(RGB)×480	dots
Color filter array	RGB vertical stripe	--
Display mode	IPS / Transmission / Normally Black	-
Gray Scale Inversion Direction	80/80/80/80	--
Eyes Viewing Direction	ALL	--
Driver IC	ST7796	--
Module size	54.66(W)×82.94(H)×2.3(T)	mm
Active area	48.96(W)×73.44(H)	mm
Dot pitch	153(W)×153(H)	um
Interface	MCU 8/9/16/18bit interface 3wrie/4wrie SPI+16/18bit RGB interface	--
Operating temperature	-20 ~ +70	°C
Storage temperature	-30 ~ +80	°C
Back Light	6White LED	--
Weight	TBD	g

CTP

ITEM	STANDARD VALUES	UNITS
CTP type	Cover Lens + sensor + FPC	--
CTP Driver IC	GT911	--
Surface Treatment	6H	--
Transmittance	≥82%	--
The cover hardness	6H	--
CTP size	57.6(W)×98(H)×1.45(T)	mm
CTP Active area	49.56(W)×70.04(H)	mm
CTP Interface	I2C	
response time	10	ms
Pointing Stick		

4. Interface Description

PIN NO.	PIN NAME	DESCRIPTION
1	LEDK	The Anode of LED power
2	LEDA	The cathode of LED power
3	NC	NC
4	VCI	Analog operating voltage.
5	IOVCC	Logic operating voltage.
6~9	IM0~IM3	MPU interface mode select pin,(FYI NOTE1)
10	GND	Power ground
11	VS	Frame synchronizing signal for RGB interface operation.
12	HS	Line synchronizing signal for RGB interface operation.
13	PCLK	Dot clock signal for RGB interface operation.
14	DE	Data enable signal for RGB interface operation.
15	GND	Power ground
16-39	D0-D23	Data bus
40	RESET	Reset pin setting either pin low initializes the LSI Must be reset after power supplied
41	RD	Read signal input terminal, Active at 'L'.
42	CS	Chip select signal input terminal, Active at 'L'
43	WR/SCL	Serial clock input for SPI interfac
44	DCX	The SPI interface (DCX): The signal for command or parameter select.
45	SDI	When IM [3]: Low, Serial in/out signal. When IM [3]: High, Serial input signal. The data is applied on the rising edge of the SCL signal.
46	SDO	Serial output signal. The data is applied on the rising edge of the SCL signal.
47	NC	NC
48	NC	NC
49	NC	NC
50	NC	NC

Note1: The System interface mode select

IM2	IM1	IM0	MPU Interface Mode	Data pin
0	0	0	8080 18-bit Interface	DB[17:0]
0	0	1	8080 9-bit Interface	DB[8:0]
0	1	0	8080 16-bit Interface	DB[15:0]
0	1	1	8080 8-bit Interface	DB[7:0],
1	0	0	Reserve	--
1	0	1	3SPI	SDA, SDO
1	1	0	MIPI	MIPI_DATA MIPI_CLOCK
1	1	1	4Line SPI	SDA, SDO

CTP

PIN NO.	PIN NAME	
1	GND	CTP Power ground
2~5	NC	NC
6	GND	CTP Power ground
7	SDA	CTP I ² C_data
8	SCL	CTP I ² C_clock.
9	RESET	CTP reset pin. Active low to enter reset state.
10	INT	CTP interruption signal.
11,12	VDD	CTP Digital Power.

5. Absolute Maximum Ratings

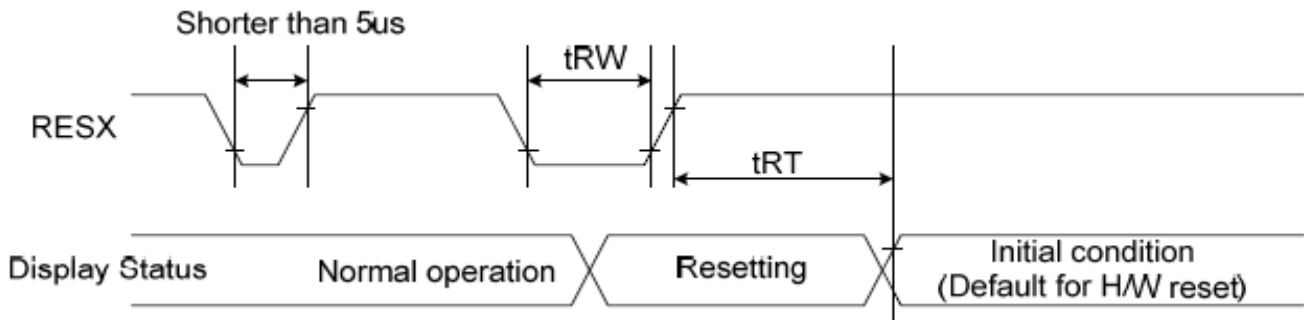
Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	3.3	V
Analog Supply Voltage	VCI	-0.3	3.3	V
Input Voltage	V _{in}	-0.3	IOVCC+0.3	V
Operating Temperature	T _{OP}	-30	70	°C
Storage Temperature	T _{ST}	-55	110	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8	3.3	V	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	V	-
Input High Voltage	V _{IH}	0.7*IOVCC	-	IOVCC	V	-
Input Low Voltage	V _{IL}	-0.3	-	0.3*IOVCC	V	-
Output High Voltage	V _{OH}	0.8*IOVCC	-	IOVCC	V	-
Output Low Voltage	V _{OL}	GND	-	0.2*IOVCC	V	-
I/O Leak Current	I _{LI}	-1	-	1	uA	-

7. Timing Characteristics

7.1 Reset Timing Characteristics



Reset Timing

Signal	Symbol	Parameter	Min	Max	Unit
RESX	t_{RW}	Reset pulse duration	10		μ S
	t_{RT}	Reset cancel		5 (note 1,5) 120 (note 1,6,7)	mS

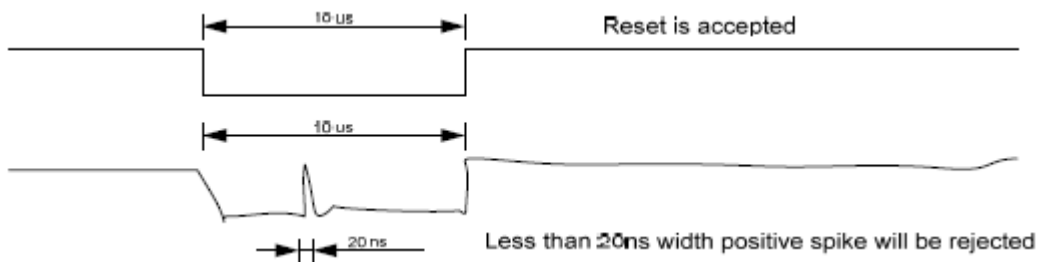
Notes:

1. The reset cancel also includes the required time for loading ID bytes, VCOM setting and other settings from the EEPROM to registers. After a rising edge of RESX, this loading is done within 5 ms after the H/W reset cancel (t_{RT}).
2. According to the Table 40, a spike due to an electrostatic discharge on the RESX line does not cause irregular system reset.

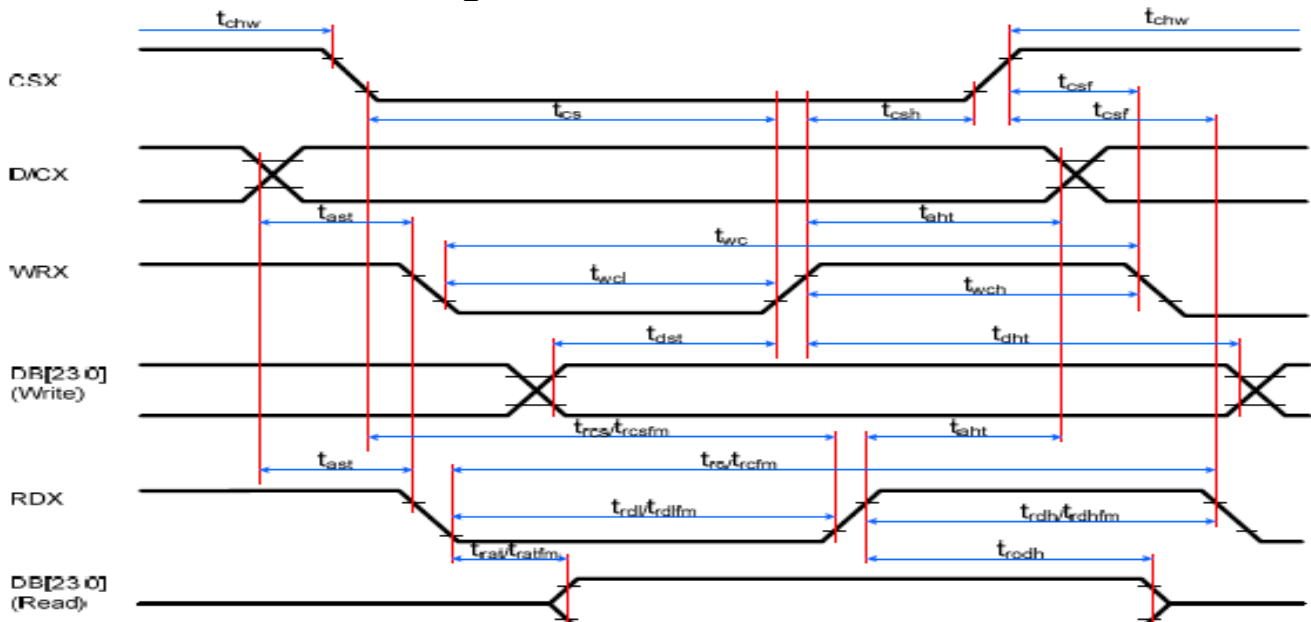
Reset Description

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

3. During the Reset period, the display will be blanked (When Reset starts in the Sleep Out mode, the display will enter the blanking sequence in at least 120 ms. The display remains the blank state in the Sleep In mode.) and then return to the default condition for the Hardware Reset.
4. Spike Rejection can also be applied during a valid reset pulse, as shown below:

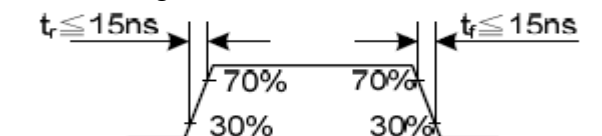


7.2 MCU 8/9/16/18-bit Timing Characteristics

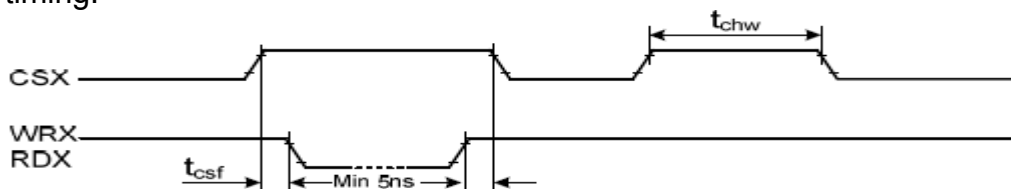


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	-
	that	Address hold time (Write/Read)	0	-	ns	-
CSX	tchwh	CSX "H" pulse width	0	-	ns	-
	tcs	Chip Select setup time (Write)	15	-	ns	-
	trcs	Chip Select setup time (Read ID)	45	-	ns	-
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	-
WRX	tcsf	Chip Select Wait time (Write/Read)	0	-	ns	-
	twc	Write cycle	30	-	ns	-
	twrh	Write Control pulse H duration	15	-	ns	-
RDX (FM)	twrh	Write Control pulse L duration	15	-	ns	-
	trcfm	Read Cycle (FM)	450	-	ns	When read from Frame Memory
	trdhfm	Read Control H duration (FM)	90	-	ns	
trdlfm	Read Control L duration (FM)	355	-	ns		
RDX (ID)	trc	Read cycle (ID)	160	-	ns	When read ID data
	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
DB [23:0], DB [17:0], DB [15:0], DB [8:0], DB [7:0]	tdst	Write data setup time	10	-	ns	For maximum, CL=30pF For minimum, CL=8pF
	tdht	Write data hold time	10	-	ns	
	trat	Read access time	-	40	ns	
	tratfm	Read access time	-	340	ns	
	trod	Read output disable time	20	80	ns	

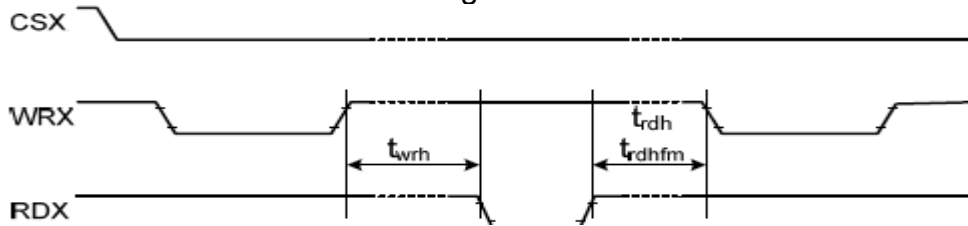
- Ta = -30 to 70 °C, IOVCC = 1.65V to 3.3V, VCI = 2.5V to 3.3V, AGND = DGND = 0V
- Logic high and low levels are specified as 30% and 70% of IOVCC for input signals.
- Input signal rising time and falling time:



- The CSX timing:

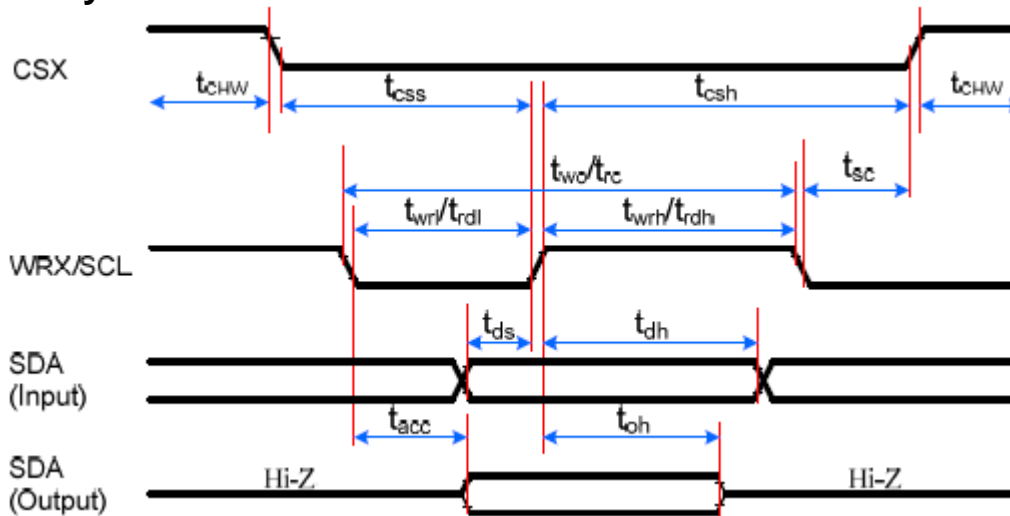


5. The Write to Read or the Read to Write timing:



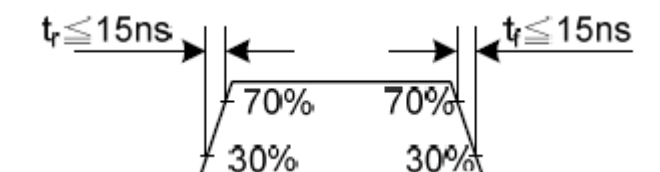
7.3 Display Serial Interface Timing Characteristics

3-wire SPI system

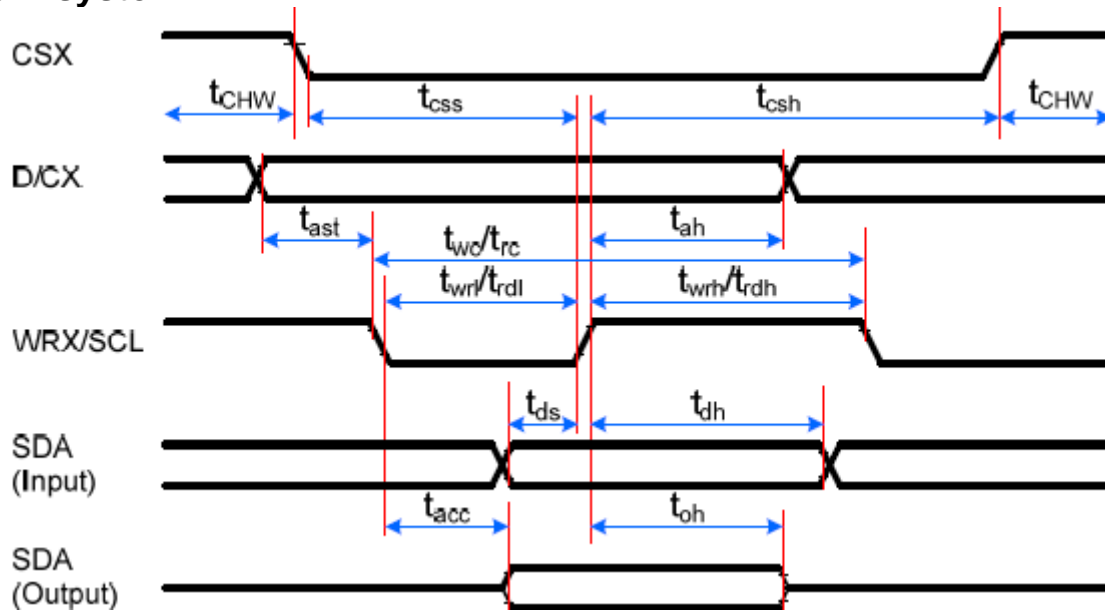


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tsc	SCL-CSX	15	-	ns	
	tchW	CSX H Pulse Width	40	-	ns	
	tcss	Chip select time (Write)	60	-	ns	
	tcsh	Chip select hold time (Read)	65	-	ns	
SCL	twc	Serial Clock Cycle (Write)	66	-	ns	
	twrh	SCL H Pulse Width (Write)	15	-	ns	
	twrl	SCL L Pulse Width (Write)	15	-	ns	
	trc	Serial Clock Cycle (Read)	150	-	ns	
	trdh	SCL H Pulse Width (Read)	60	-	ns	
	trdl	SCL L Pulse Width (Read)	60	-	ns	
SDA/SDI (Input)	tds	Data setup time (Write)	10	-	ns	
	tdh	Data hold time (Write)	10	-	ns	
SDA/SDO (Output)	tacc	Access time (Read)	10	50	ns	For maximum CL=30pF
	toh	Output disable time (Read)	15	50	ns	For minimum CL=8pF

Note: Ta = -30 to 70 °C, IOVCC = 1.65V to 3.6V, VCI = 2.5V to 3.6V, AGND = DGND = 0V, T = 10+/-0.5ns



4-wire SPI system

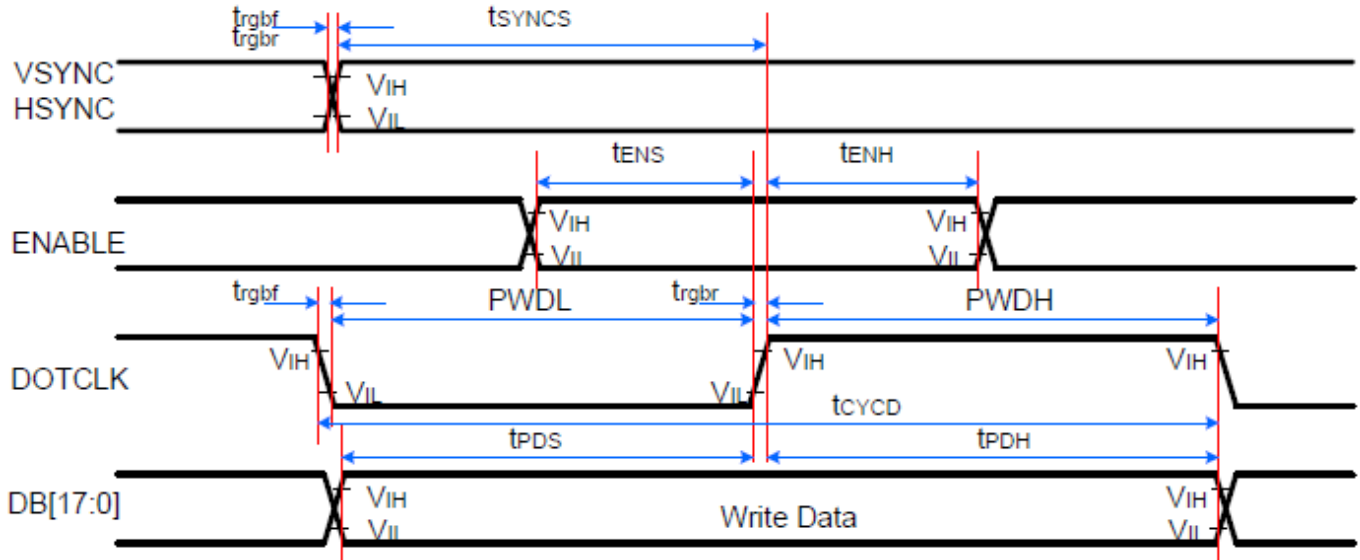


Signal	Symbol	Parameter	min	max	Unit	Description
CSX	t_{css}	Chip select time (Write)	15	-	ns	
	t_{csh}	Chip select hold time (Read)	15	-	ns	
	t_{CHW}	CS H pulse width	40	-	ns	
SCL	t_{wc}	Serial clock cycle (Write)	50	-	ns	
	t_{wrh}	SCL H pulse width (Write)	10	-	ns	
	t_{wrl}	SCL L pulse width (Write)	10	-	ns	
	t_{rc}	Serial clock cycle (Read)	150	-	ns	
	t_{rdh}	SCL H pulse width (Read)	60	-	ns	
	t_{rdl}	SCL L pulse width (Read)	60	-	ns	
D/CX	t_{as}	D/CX setup time	10	-	ns	
	t_{ah}	D/CX hold time (Write/Read)	10	-	ns	
SDA/SDI (Input)	t_{ds}	Data setup time (Write)	10	-	ns	
	t_{dh}	Data hold time (Write)	10	-	ns	
SDA/SDO (Output)	t_{acc}	Access time (Read)	10	50	ns	For maximum CL=30pF
	t_{od}	Output disable time (Read)	15	50	ns	For minimum CL=8pF

Notes:

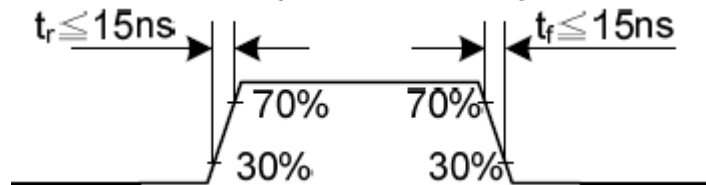
- $T_a = -30$ to 70 °C, $IOVCC = 1.65V$ to $3.3V$, $VCI = 2.5V$ to $3.3V$, $AGND = DGND = 0V$, $T = 10 \pm 0.5ns$.
- Does not include signal rising and falling times.

7.4 Parallel 18/16-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC/ HSYNC	t_{SYNCS}	VSYNC/HSYNC setup time	15	-	ns	16-/18-/24-bit bus RGB interface mode
	t_{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
ENABLE	t_{ENS}	ENABLE setup time	15	-	ns	
	t_{ENH}	ENABLE hold time	15	-	ns	
DB [23:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PWDH	DOTCLK high-level period	20	-	ns	
	PWDL	DOTCLK low-level period	20	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	t_{r}, t_{f}	DOTCLK, HSYNC, VSYNC rise/fall time	-	15	ns	

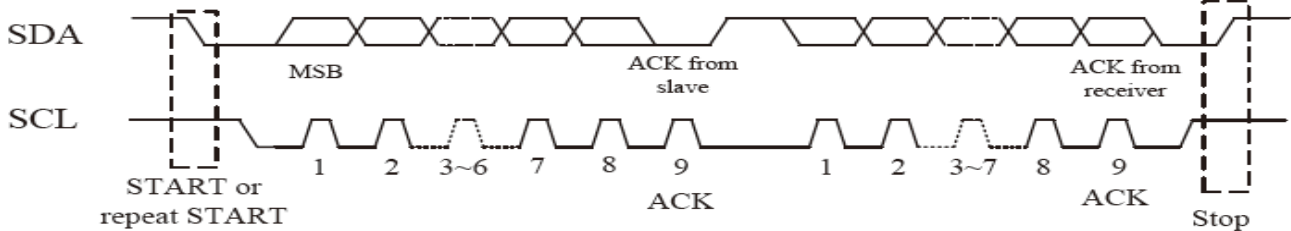
Note: $T_a = -30$ to 70 °C, $IOVCC = 1.65V$ to $3.3V$, $VCI = 2.5V$ to $3.3V$, $AGND = DGND = 0V$



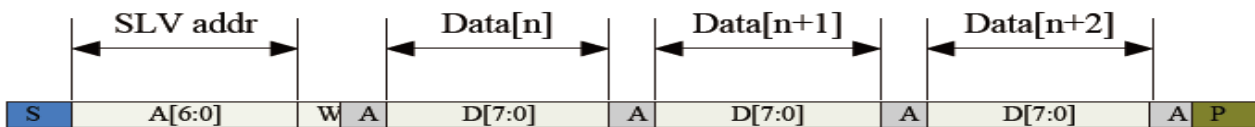
7.5 CTP Timing characteristics

7.5.1 Serial Interface

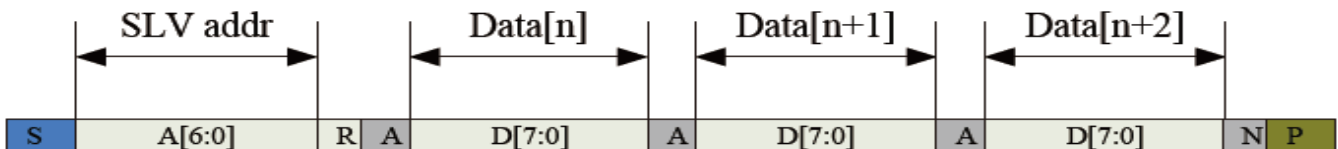
I²C



I2C Serial Data Transfer Format



I2C master write, slave read



I2C master read, slave write

Table 2-1 lists the meanings of the mnemonics used in the above figures.

Mnemonics Description

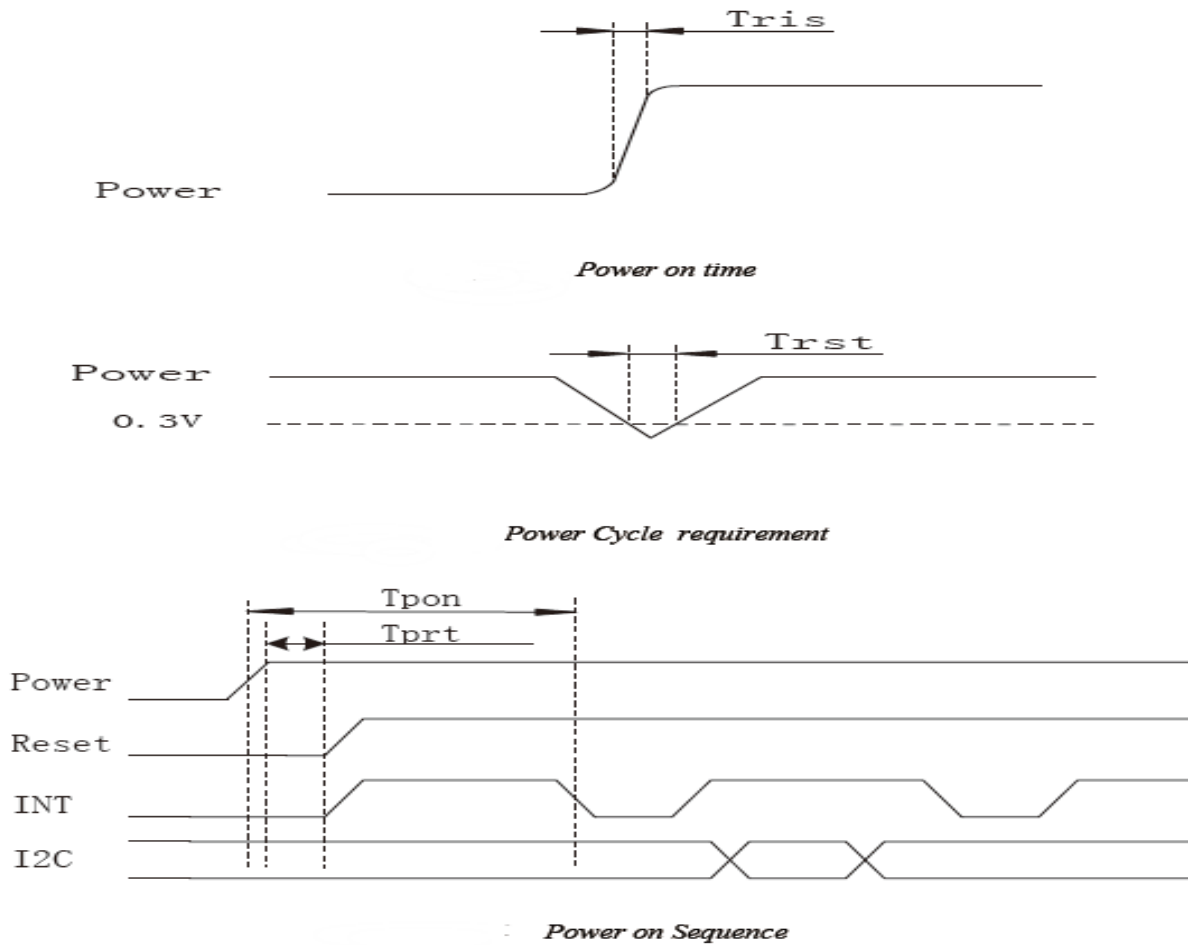
Mnemonics	Description
S	I2C Start or I2C Restart
A[6:0]	Slave address
R/W	READ/WRITE bit, '1' for read, '0' for write
A(N)	ACK(NACK)
P	STOP: the indication of the end of a packet (if this bit is missing, S will indicate the end of the current packet and the beginning of the next packet)

I2C Interface Timing Characteristics is shown in Table 2-2.

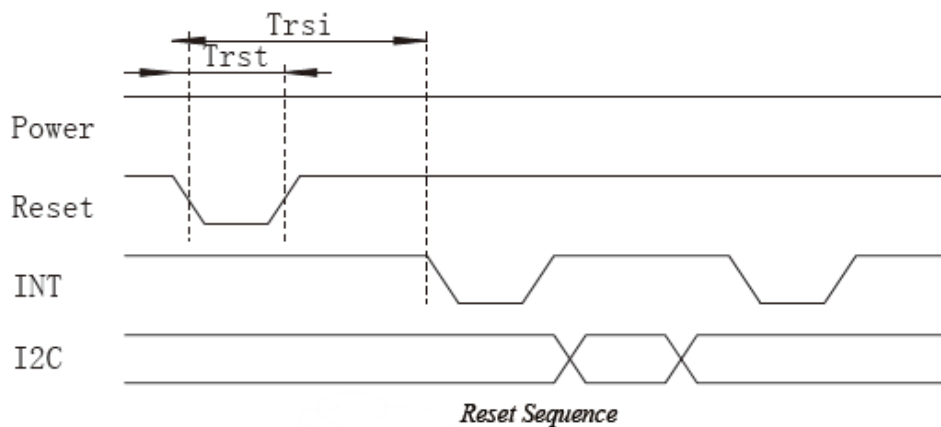
I2C Timing Characteristics

Parameter	Min	Max	Unit
SCL frequency	10	400	KHz
Bus free time between a STOP and START condition	4.7	\	us
Hold time (repeated) START condition	4.0	\	us
Data setup time	250	\	ns
Setup time for a repeated START condition	4.7	\	us
Setup Time for STOP condition	4.0	\	us

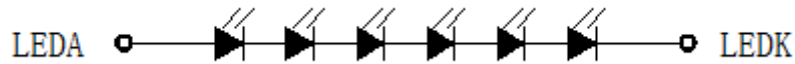
7.5.2 POWER NO /Reset/Wake Sequence



Reset time must be enough to guarantee reliable reset, the time of starting to report point after resetting approach to the time of starting to report point after powering on.



8. Backlight Characteristics



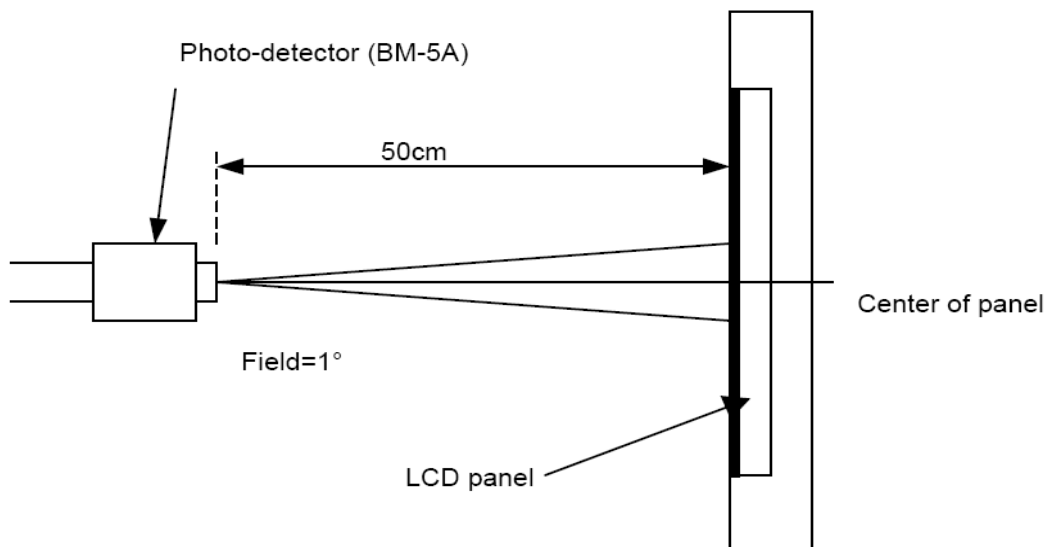
BL CIRCUIT DIAGRAM

Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	16.8	19.2	21	V	If=20mA
Supply Current	If	-	20	-	mA	-
Luminous Intensity for LCM	-	250	300	-	cd/m ²	If=20mA
Uniformity for LCM	-	80	-	-	%	If=20mA
Life Time	-	-	20000	-	Hr	If=20mA
Backlight Color	White					

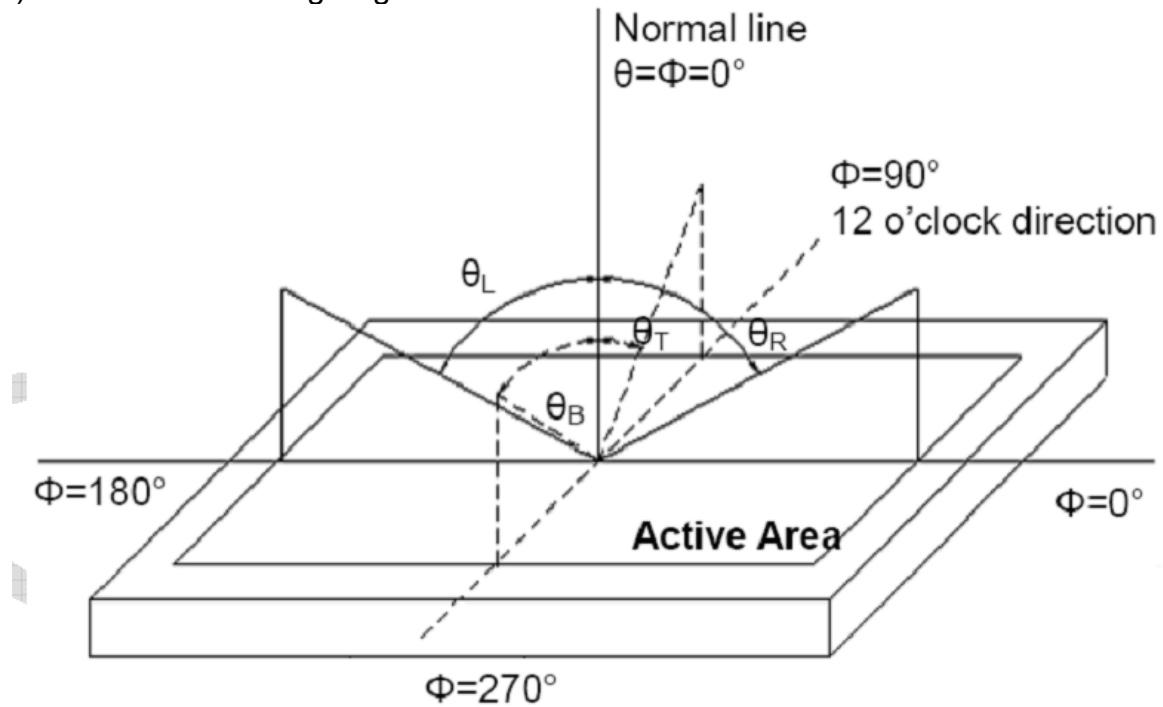
9. Optical Characteristics

Item	Conditions	Min.	Typ.	Max.	Unit	Note	
Viewing Angle (CR>10)	Horizontal	θ_L	-	80	-	degree	(1),(2),(6)
		θ_R	-	80	-		
	Vertical	θ_T	-	80	-		
		θ_B	-	80	-		
Contrast Ratio	Center	-	700	-	-	(1),(3),(6)	
Response Time	Rising + Falling	-	30	-	ms	(1),(4),(6)	
CF Color Chromaticity (CIE1931)	Red x	Typ. -0.05	TBD	Typ. +0.05	-	(1), (6)	
	Red y		TBD		-		
	Green x		TBD		-		
	Green y		TBD		-		
	Blue x		TBD		-		
	Blue y		TBD		-		
	White x		TBD		-		
	White y		TBD		-		

Note (1) Measurement Setup: The LCD module should be stabilized at given temp. 25°C for 15 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 15 minutes in a windless room.



Note (2) Definition of Viewing Angle



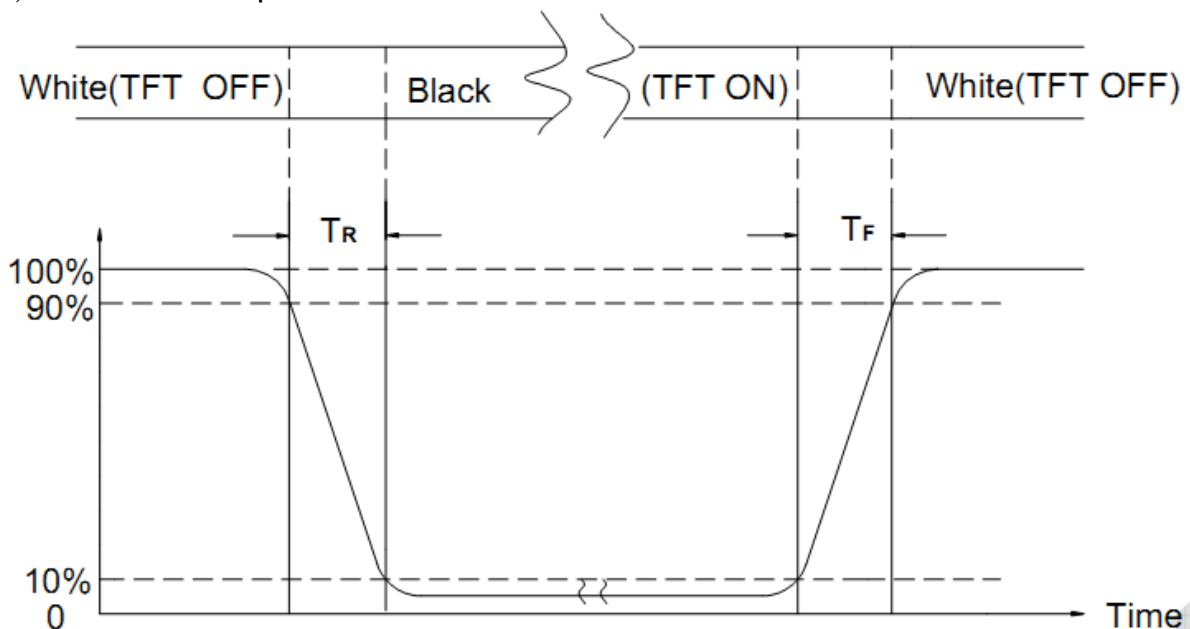
Note (3) Definition Of Contrast Ratio (CR)

The contrast ratio can be calculated by the following expression

$$\text{Contrast Ratio (CR)} = L63 / L0$$

L63: Luminance of gray level 63, L0: Luminance of gray level 0

Note (4) Definition of response time



Note (5) Definition of Transmittance (Module is without signal input)

$$\text{Transmittance} = \text{Center Luminance of LCD} / \text{Center Luminance of Back Light} \times 100\%$$

Note (6) Definition of color chromaticity (CIE1931)

Color coordinates measured at the center point of LCD

10. Reliability Test Conditions and Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
<input type="checkbox"/>	High Temperature Storage	80°C±2°C×96Hours	Inspection after 2~4hours storage at room temperature, the samples should be free from defects: 1, Air bubble in the LCD. 2, Seal leak. 3, Non-display. 4, Missing segments. 5, Glass crack. 6, Current IDD is twice higher than initial value. 7, The surface shall be free from damage. 8, The electric characteristic requirements shall be satisfied.
<input type="checkbox"/>	Low Temperature Storage	-30°C±2°C×96Hours	
<input type="checkbox"/>	High Temperature Operating	70°C±2°C×96Hours	
<input type="checkbox"/>	Low Temperature Operating	-20°C±2°C×96Hours	
<input type="checkbox"/>	Temperature Cycle(Storage)	-20°C ↔ 25°C ↔ 70°C (30min) ← (5min) → (30min) 1cycle Total 10cycle	
<input type="checkbox"/>	Damp Proof Test (Storage)	50°C±5°C×90%RH×96Hours	
<input type="checkbox"/>	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5MM X,Y,Z direction for total 3hours (packing condition test will be tested by a carton)	
<input type="checkbox"/>	Drooping Test	Drop to the ground from 1M height one time every side of carton. (packing condition test will be tested by a carton)	
<input type="checkbox"/>	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1, The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test, Pure water(Resistance > 10MΩ)should be used.
- 4,In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.
- 5, EL evaluation should be accepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Inspection Standard

11.1. QUALITY :

THE QUALITY OF GOODS SUPPLIED TO PURCHASER SHALL COME UP TO THE FOLLOWING STANDARD.

11.1.1. THE METHOD OF PRESERVING GOODS

AFTER DELIVERY OF GOODS FROM AMSON TO PURCHASER. PURCHASER SHALL CONTROL THE LCM AT -10 °C TO 40°C ,AND IT MIGHT BE DESIRABLE TO KEEP AT THE NORMAL ROOM TEMPERATURE AND HUMIDITY UNTIL INCOMING INSPECTION OR THROWING INTO PROCESS LINE.

11.1.2. INCOMING INSPECTION

(A) THE METHOD OF INSPECTION

IF PURCHASER MAKE AN INCOMING INSPECTION , A SAMPLING PLAN SHALL BE APPLIED ON THE CONDITION THAT QUALITY OF ONE DELIVERY SHALL BE REGARDED AS ONE LOT.

(B) THE STANDARD OF QUALITY

ISO-2859-1 (SAME AS MIL-STD-105E) , LEVEL II SINGLE PLAN.

CLASS	AQL(%)
CRITICAL	0.4 %
MAJOR	0.65 %
MINOR	1.5 %
TOTAL	1.5 %

EVERY ITEM SHALL BE INSPECTED ACCORDING TO THE CLASS.

(C) MEASURE

IF AS THE RESULT OF ABOVE RECEIVING INSPECTION , A LOT OUT IS DISCOVERED. PURCHASER SHALL BE INFORM SELLER OF IT WITHIN SEVEN DAYS. BUT FIRST SHIPMENT WITHIN FOURTEEN DAYS.

11.1.3. WARRANTY POLICY

AMSON WILL PROVIDE ONE-YEAR WARRANTY FOR THE PRODUCTS ONLY IF UNDER SPECIFICATION OPERATING CONDITIONS. AMSON WILL REPLACE NEW PRODUCTS FOR THESE DEFECT PRODUCTS WHICH UNDER WARRANTY PERIOD AND BELONG TO THE RESPONSIBILITY OF AMSON.

11.2. CHECKING CONDITION

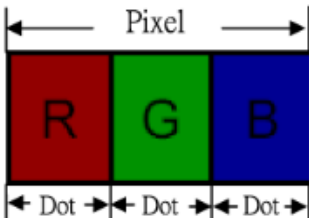
11.2.1. CHECKING DIRECTION SHALL BE IN THE 45 DEGREE AREA TO FACE THE SAMPLE.

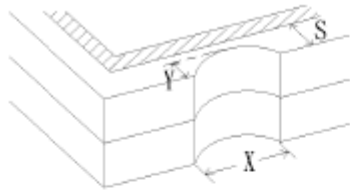
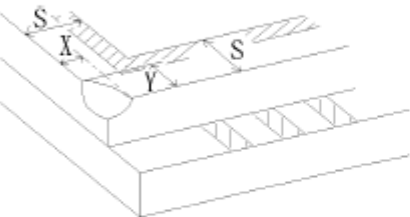
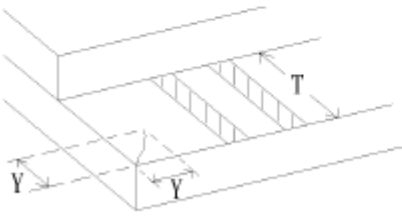
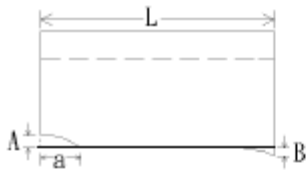
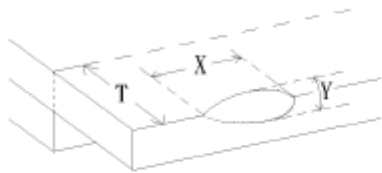
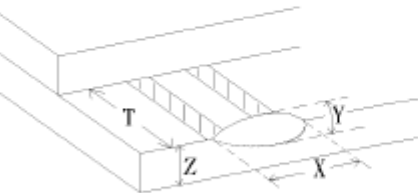
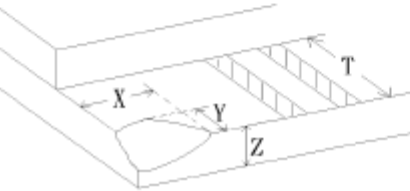
11.2.2. CHECKER SHALL SEE OVER 300±25 mm. WITH BARE EYES FAR FROM SAMPLE AND USING 2 PCS. OF 20W FLUORESCENT LAMP.

11.3. INSPECTION PLAN :

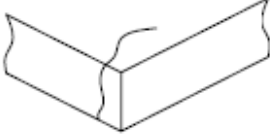
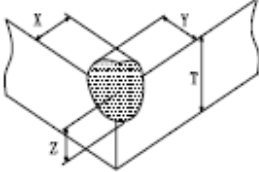
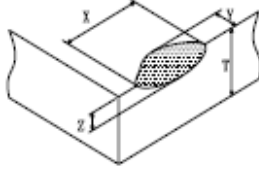
CLASS	ITEM	JUDGEMENT	CLASS
PACKING & INDICATE	1. OUTSIDE AND INSIDE PACKAGE	"MODEL NO." , "LOT NO." AND "QUANTITY" SHOULD INDICATE ON THE PACKAGE.	Minor
	2. MODEL MIXED AND QUANTITY	OTHER MODEL MIXED.....REJECTED QUANTITY SHORT OR OVER.....REJECTED	Critical
	3. PRODUCT INDICATION	"MODEL NO." SHOULD INDICATE ON THE PRODUCT	Major
ASSEMBLY	4. DIMENSION, LCD GLASS SCRATCH AND SCRIBE DEFECT.	ACCORDING TO SPECIFICATION OR DRAWING.	Major
APPEARANCE	5. VIEWING AREA	POLARIZER EDGE OR LCD'S SEALING LINE IS VISABLE IN THE VIEWING AREAREJECTED	Minor
	6. BLEMISH · BLACK SPOT · WHITE SPOT IN THE LCD AND LCD GLASS CRACKS	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	7. BLEMISH · BLACK SPOT WHITE SPOT AND SCRATCH ON THE POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	8. BUBBLE IN POLARIZER	ACCORDING TO STANDARD OF VISUAL INSPECTION(INSIDE VIEWING AREA)	Minor
	9. LCD'S RAINBOW COLOR	STRONG DEVIATION COLOR (OR NEWTON RING) OF LCD.....REJECTED. OR ACCORDING TO LIMITED SAMPLE (IF NEEDED, AND INSIDE VIEWING AREA)	Minor
ELECTRICAL	10. ELECTRICAL AND OPTICAL CHARACTERISTICS (CONTRAST · VOP · CHROMATICITY ... ETC)	ACCORDING TO SPECIFICATION OR DRAWING . (INSIDE VIEWING AREA)	Critical
	11.MISSING LINE	MISSING DOT · LINE · CHARACTERREJECTED	Critical
	12.SHORT CIRCUIT · WRONG PATTERN DISPLAY	NO DISPLAY · WRONG PATTERN DISPLAY · CURRENT CONSUMPTION OUT OF SPECIFICATION..... REJECTED	Critical
	13. DOT DEFECT (FOR COLOR AND TFT)	ACCORDING TO STANDARD OF VISUAL INSPECTION	Minor

11.4. STANDARD OF VISUAL INSPECTION

NO.	CLASS	ITEM	JUDGEMENT																				
11.4.1	MINOR	BLACK AND WHITE SPOT FOREIGN MATERIEL DUST IN THE CELL BLEMISH SCRATCH	<p>(A) ROUND TYPE: unit : mm.</p> <table border="1"> <thead> <tr> <th>DIAMETER (mm.)</th> <th>ACCEPTABLE Q'TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.1$</td> <td>DISREGARD</td> </tr> <tr> <td>$0.1 < \Phi \leq 0.25$</td> <td>3 (Distance>5mm)</td> </tr> <tr> <td>$0.25 < \Phi$</td> <td>0</td> </tr> </tbody> </table> <p>NOTE: $\Phi = (\text{LENGTH} + \text{WIDTH}) / 2$</p> <p>(B) LINEAR TYPE: unit : mm.</p> <table border="1"> <thead> <tr> <th>LENGTH</th> <th>WIDTH</th> <th>ACCEPTABLE Q'TY</th> </tr> </thead> <tbody> <tr> <td>-----</td> <td>$W \leq 0.03$</td> <td>DISREGARD</td> </tr> <tr> <td>$L \leq 5.0$</td> <td>$0.03 < W \leq 0.07$</td> <td>3 (Distance>5mm)</td> </tr> <tr> <td>-----</td> <td>$0.07 < W$</td> <td>FOLLOW ROUND TYPE</td> </tr> </tbody> </table>	DIAMETER (mm.)	ACCEPTABLE Q'TY	$\Phi \leq 0.1$	DISREGARD	$0.1 < \Phi \leq 0.25$	3 (Distance>5mm)	$0.25 < \Phi$	0	LENGTH	WIDTH	ACCEPTABLE Q'TY	-----	$W \leq 0.03$	DISREGARD	$L \leq 5.0$	$0.03 < W \leq 0.07$	3 (Distance>5mm)	-----	$0.07 < W$	FOLLOW ROUND TYPE
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$L \leq 5.0$	$0.03 < W \leq 0.07$	3 (Distance>5mm)																					
-----	$0.07 < W$	FOLLOW ROUND TYPE																					
11.4.2	MINOR	BUBBLE IN POLARIZER DENT ON POLARIZER	<p style="text-align: right;">unit : mm.</p> <table border="1"> <thead> <tr> <th>DIAMETER</th> <th>ACCEPTABLE Q'TY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>DISREGARD</td> </tr> <tr> <td>$0.2 < \Phi \leq 0.5$</td> <td>2 (Distance>5mm)</td> </tr> <tr> <td>$0.5 < \Phi$</td> <td>0</td> </tr> </tbody> </table>	DIAMETER	ACCEPTABLE Q'TY	$\Phi \leq 0.2$	DISREGARD	$0.2 < \Phi \leq 0.5$	2 (Distance>5mm)	$0.5 < \Phi$	0												
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$0.5 < \Phi$	0																						
11.4.3	MINOR	Dot Defect	<table border="1"> <thead> <tr> <th>Items</th> <th>ACC. Q'TY</th> </tr> </thead> <tbody> <tr> <td>Bright dot</td> <td>$N \leq 4$</td> </tr> <tr> <td>Dark dot</td> <td>$N \leq 4$</td> </tr> </tbody> </table> <p>Pixel Define :</p>  <p>Note 1: The definition of dot: The size of a defective dot over 1/2 of whole dot is regarded as one defective dot.</p> <p>Note 2: Bright dot: Dots appear bright and unchanged in size in which LCD panel is displaying under black pattern.</p> <p>Note 3: Dark dot: Dots appear dark and unchanged in size in which LCD panel is displaying under pure red, green, blue pattern.</p>	Items	ACC. Q'TY	Bright dot	$N \leq 4$	Dark dot	$N \leq 4$														
Items	ACC. Q'TY																						
Bright dot	$N \leq 4$																						
Dark dot	$N \leq 4$																						

NO.	CLASS	ITEM	JUDGEMENT
11.4.4	MINOR	LCD GLASS CHIPPING	 $Y > S$ Reject
11.4.5	MINOR	LCD GLASS CHIPPING	 $X \text{ or } Y > S$ Reject
11.4.6	MAJOR	LCD GLASS GLASS CRACK	 $Y > (1/2) T$ Reject
11.4.7	MAJOR	LCD GLASS SCRIBE DEFECT	 <ol style="list-style-type: none"> $a > L/3$, $A > 1.5\text{mm}$. Reject B : ACCORDING TO DIMENSION
11.4.8	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL AREA)	 $\Phi = (x+y)/2 > 2.5 \text{ mm}$ Reject
11.4.9	MINOR	LCD GLASS CHIPPING (ON THE TERMINAL SURFACE)	 $Y > (1/3) T$ Reject
11.4.10	MINOR	LCD GLASS CHIPPING	 $Y > T$ Reject

11.5 INSPECTION STANDARD OF TOUCH PANEL

NO.	CLASS	ITEMS		JUDGEMENT		
11.5.1	MAJOR	Touch Panel Crack			Reject	
11.5.2	MINOR	Touch Panel Chipping	Corner		$X \leq 2\text{mm}, Y \leq 2\text{mm}, Z < 1/2T$	Accept
			Edge		$X \leq 3\text{mm}, Y \leq 3\text{mm}, Z < 1/2T$	Accept
11.5.3	MINOR	Scratch Dust and Foreign material (Linear Type)		$W \leq 0.05, L \leq 20\text{mm}$	Accept	
				$0.05\text{mm} < W \leq 0.07\text{mm}; L \leq 10.0\text{mm}$ Distance between scratch $> 5.0\text{mm}$	Accept 3 ea Max.	
				$W > 0.07\text{mm}$	Reject	
11.5.4	MINOR	Scratch Dust and Foreign material (Round Type: $\Phi = (\text{Length} + \text{Width})/2$)		$\Phi \leq 0.25\text{mm}$	Accept	
				$0.25\text{mm} < \Phi \leq 0.35\text{mm}$ Distance between spots $> 5.0\text{mm}$	Accept 5 ea Max.	
				$\Phi > 0.35\text{mm}$	Reject	
11.5.5	MINOR	Touch Panel Dent / Fish Eyes		$\Phi \leq 0.35\text{mm}$	Accept	
				$0.35\text{mm} < \Phi \leq 1.0\text{mm}$ Distance $> 5.0\text{mm}$	Accept 3 ea Max.	
				$\Phi > 1.0\text{mm}$	Reject	
11.5.6	MINOR	Touch Panel Air Bubble		$\Phi \leq 0.2\text{mm}$	Accept	
				$0.2\text{mm} < \Phi \leq 0.5\text{mm}$ Distance between bubbles $> 5.0\text{mm}$	Accept 3 ea Max.	
				$\Phi > 0.5\text{mm}$	Reject	
11.5.7	MINOR	Touch Panel Printing area Scratch		$W \leq 0.05\text{mm}, L \leq 5\text{mm}$ Distance between scratch $> 5.0\text{mm}$	Accept 3 ea Max.	
				$W > 0.05\text{mm}$ or $L > 5\text{mm}$ ($W > 0.05$ Follow 11.5.4 Round type)	Reject	
11.5.8	MINOR	Touch Panel White Haze Mark / Dust		Can not be removed	Reject	

12. Handling Precautions

12.1 Mounting method

The LCD panel of AMSON TFT module consists of two thin glass plates with polarizers which easily be damaged. And since the module is so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[Recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns

Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl) , Sulfur (S)

If goods were sent without being silicon coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happens by miss-handling or using some materials such as Chlorine (Cl), Sulfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module uses C-MOS LSI drivers, so we recommend that you:

Connect any unused input terminal to VDD or GND, do not input any signals before power is turned on, and ground your body, work/assembly areas, and assembly equipment to protect against static electricity.

12.4 packing

- Module employs LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage than the limit causes the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- Slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storing

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it. And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
[It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution for Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to AMSON TFT , and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD